GREEN AMERICA
CLEAN ELECTRONICS
PRODUCTION NETWORK
A project of the Center for Sustainability Solutions

CEPN Definitions

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Definitions

Cleaning Products: Chemicals and chemical mixtures used to remove contaminants, unwanted materials and/or manufacturing processing residues (e.g. lubricants, adhesives, solder flux residues, plastic residue, mold release residues, etc.) from:

- Individual parts, subcomponents, assemblies, process substrates and/or final assembled products; and/or
- Manufacturing equipment used to manufacture individual components or final product

Examples of chemical products used for cleaning include solvents, aqueous detergent solutions, stencil/ink removers, adhesive removers, solvent vapor degreaser solutions, ultrasonic parts cleaner solutions, photo-resist strippers, solder defluxing solutions, etc.

Note that fluxes and mold release agents are not considered cleaning products.

Closed Process: Enclosed production, or processes with equivalent containment conditions, without likelihood of exposure. The enclosed transfers inherent to the process, including sampling, are included. Unenclosed transfers to charge/discharge the process are not included. (Adapted from EU PROC 1)

Photoresist Stripping: The removal of unwanted photoresist layers from the wafer. Its objective is to eliminate the photoresist material from the wafer as quickly as possible, without allowing any surface materials under the resist to get attacked by the chemicals used. Resist stripping can be classified into 1) organic stripping; 2) inorganic stripping; and 3) dry stripping.

Source: EESEMI Comprehensive Reference on Semiconductor Manufacturing (https://www.eesemi.com/wafer-cleaning.htm)

Process Chemicals: Chemicals (individual chemicals or mixtures) used during the manufacture and/or finishing of a product and/or maintenance of related production equipment that are not intentionally fully incorporated into the product. Examples of process chemicals include cleaning agents, lubricants, photochemicals, plating agents, refrigerants, hydraulic fluids, and solvents, including volatile chemicals emitted from adhesives, inks and coatings during manufacturing.